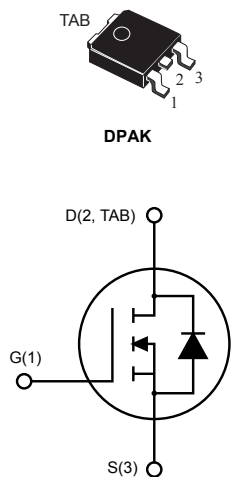


N-channel 650 V, 0.230 Ω typ., 12 A MDmesh™ M5 Power MOSFET in a DPAK package



AM01475v1_noZen

Features

Order codes	V_{DS} at $T_{jmax.}$	$R_{DS(on)}$ max.	I_D
STD16N65M5	710 V	0.279 Ω	12 A

- Extremely low $R_{DS(on)}$
- Low gate charge and input capacitance
- Excellent switching performance
- 100% avalanche tested

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET based on the MDmesh™ M5 innovative vertical process technology combined with the well-known PowerMESH™ horizontal layout. The resulting product offers extremely low on-resistance, making it particularly suitable for applications requiring high power and superior efficiency.



Product status link

[STD16N65M5](#)

Product summary

Order code	STD16N65M5
Marking	16N65M5
Package	DPAK
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 25	V
I_D	Drain current (continuous) at $T_C = 25\text{ }^{\circ}\text{C}$	12	A
I_D	Drain current (continuous) at $T_C = 100\text{ }^{\circ}\text{C}$	7.3	A
$I_{DM}^{(1)}$	Drain current (pulsed)	48	A
P_{TOT}	Total power dissipation at $T_C = 25\text{ }^{\circ}\text{C}$	90	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15	V/ns
T_J	Operating junction temperature range	-55 to 150	$^{\circ}\text{C}$
T_{stg}	Storage temperature range		

1. Pulse width limited by safe operating area.
2. $I_{SD} \leq 12\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{s}$, $V_{DD} = 400\text{ V}$, $V_{DS(peak)} < V_{(BR)DSS}$.

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	1.38	$^{\circ}\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	50	$^{\circ}\text{C}/\text{W}$

1. When mounted on 1inch² FR-4 board, 2 oz Cu.

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_J Max)	4	A
E_{AS}	Single pulse avalanche energy (starting $T_J = 25\text{ }^{\circ}\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	200	mJ

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 1 mA, V _{GS} = 0 V	650			V
I _{DSS}	Zero gate voltage drain current	V _{GS} = 0 V, V _{DS} = 650 V,			1	μA
		V _{GS} = 0 V, V _{DS} = 650 V, T _C = 125 °C ⁽¹⁾			100	μA
I _{GSS}	Gate body leakage current	V _{DS} = 0 V, V _{GS} = ±25 V			100	nA
V _{GS(th)}	Gate threshold voltage	V _{DS} = V _{GS} , I _D = 250 μA	3	4	5	V
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10 V, I _D = 6 A		0.230	0.279	Ω

1. Defined by design, not subject to production test.

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C _{iss}	Input capacitance	V _{DS} = 100 V, f = 1 MHz, V _{GS} = 0 V	-	1250	-	pF
C _{oss}	Output capacitance			30		
C _{rss}	Reverse transfer capacitance			3		
C _{o(tr)} ⁽¹⁾	Equivalent capacitance time related	V _{DS} = 0 to 520 V, V _{GS} = 0 V	-	100	-	pF
C _{o(er)} ⁽²⁾	Equivalent capacitance energy related		-	30	-	pF
R _g	Gate input resistance	f = 1 MHz open drain	-	2	-	Ω
Q _g	Total gate charge	V _{DD} = 520 V, I _D = 12 A, V _{GS} = 0 to 10 V (see Figure 15. Test circuit for gate charge behavior)	-	31	-	nC
Q _{gs}	Gate-source charge			8		
Q _{gd}	Gate-drain charge			12		

1. C_{o(tr)} time related is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.

2. C_{o(er)} energy related is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(v)}$	Voltage delay time	$V_{DD} = 400\text{ V}$, $I_D = 8\text{ A}$, $R_G = 4.7\ \Omega$, $V_{GS} = 10\text{ V}$ (see Figure 16. Test circuit for inductive load switching and diode recovery times and Figure 19. Switching time waveform)	-	25	-	ns
$t_{r(v)}$	Voltage rise time			7		
$t_{f(i)}$	Current fall time			6		
$t_{c(off)}$	Crossing time			8		

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I _{SD}	Source-drain current		-		12	A
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)				48	
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 12 A, V _{GS} = 0 V	-		1.5	V
t _{rr}	Reverse recovery time	I _{SD} = 12 A, di/dt = 100 A/μs	-	300		ns
Q _{rr}	Reverse recovery charge	V _{DD} = 100 V (see Figure 16. Test circuit for inductive load switching and diode recovery times)		3.5		μC
I _{RRM}	Reverse recovery current			23		A
t _{rr}	Reverse recovery time	I _{SD} = 12 A, di/dt = 100 A/μs	-	350		ns
Q _{rr}	Reverse recovery charge	V _{DD} = 100 V (see Figure 16. Test circuit for inductive load switching and diode recovery times)		4		μC
I _{RRM}	Reverse recovery current			24		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics curves

Figure 1. Safe operating area

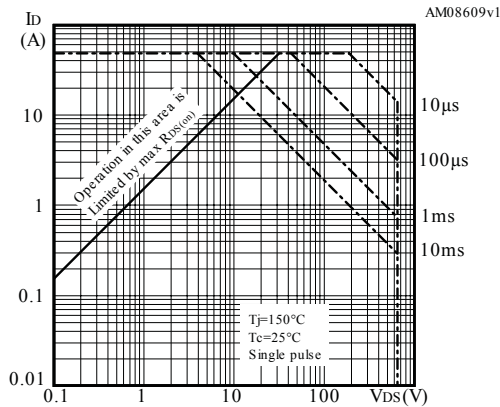


Figure 2. Thermal impedance

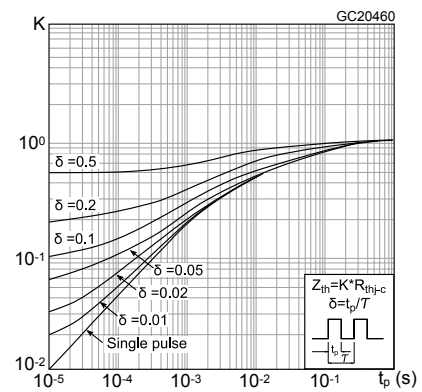


Figure 3. Output characteristics

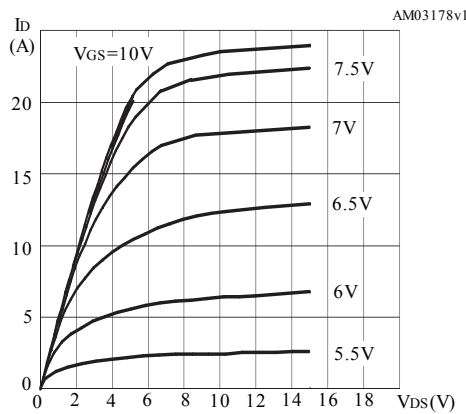


Figure 4. Transfer characteristics

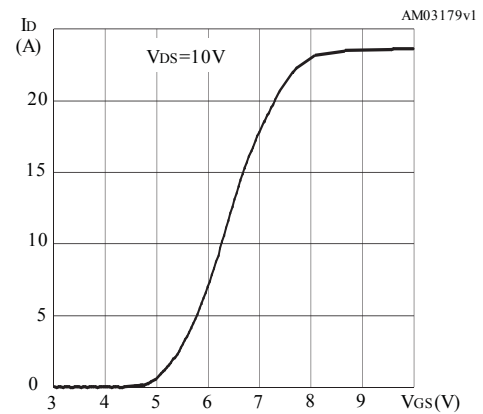


Figure 5. Normalized $V_{(BR)DSS}$ vs temperature

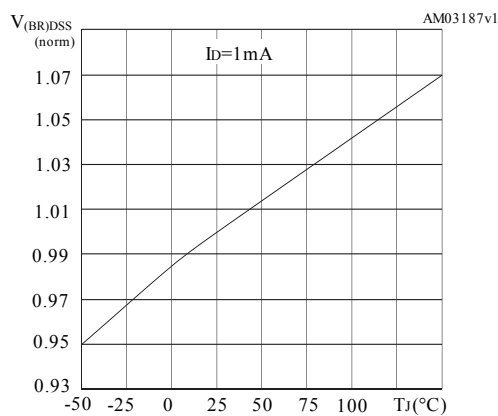


Figure 6. Static drain-source on resistance

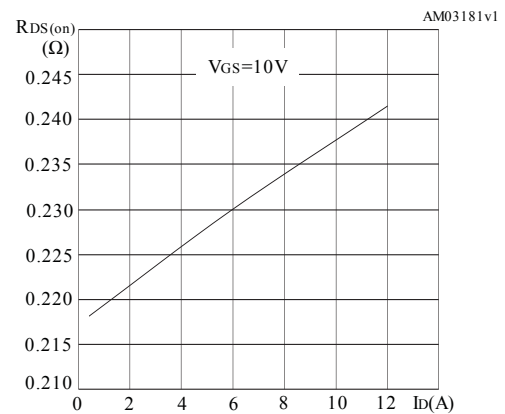


Figure 7. Output capacitance stored energy

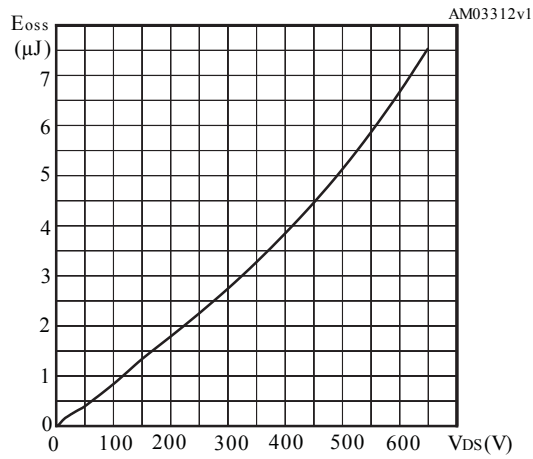


Figure 8. Capacitance variations

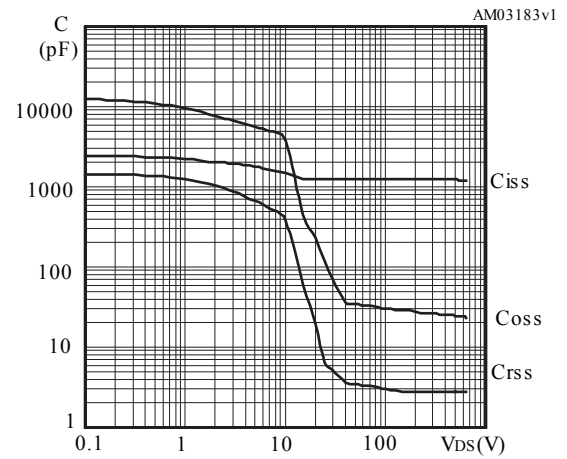


Figure 9. Gate charge vs gate-source voltage

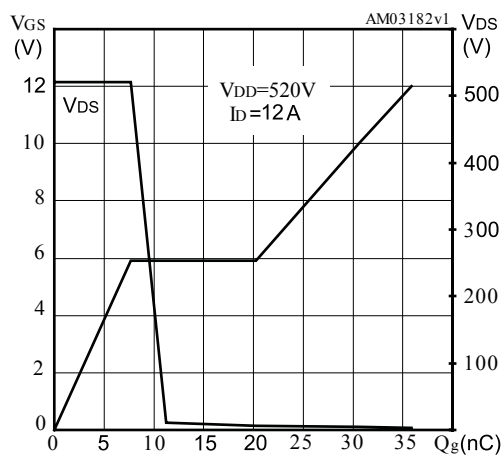


Figure 10. Normalized on resistance vs temperature

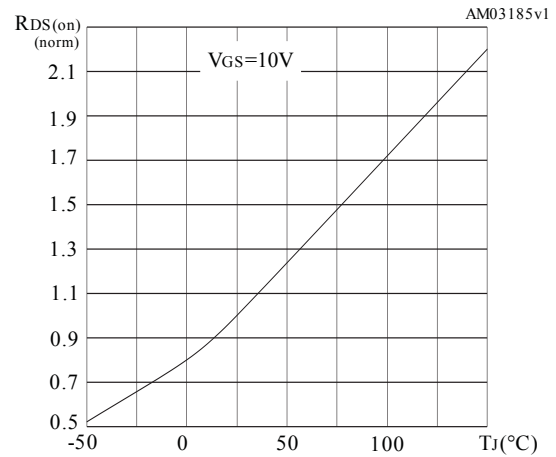


Figure 11. Normalized gate threshold voltage vs temperature

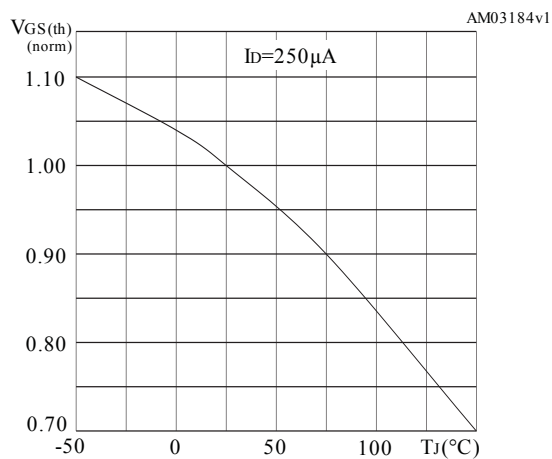


Figure 12. Source-drain diode forward characteristics

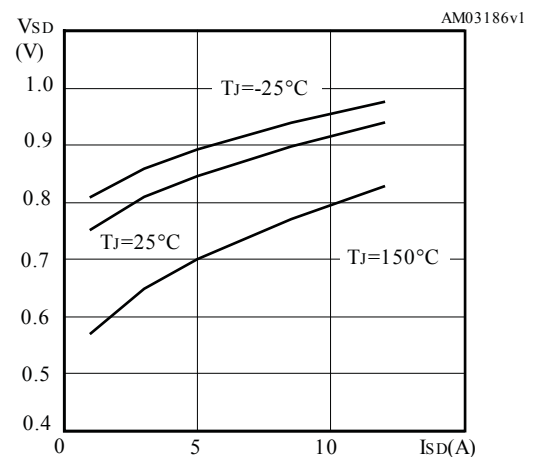
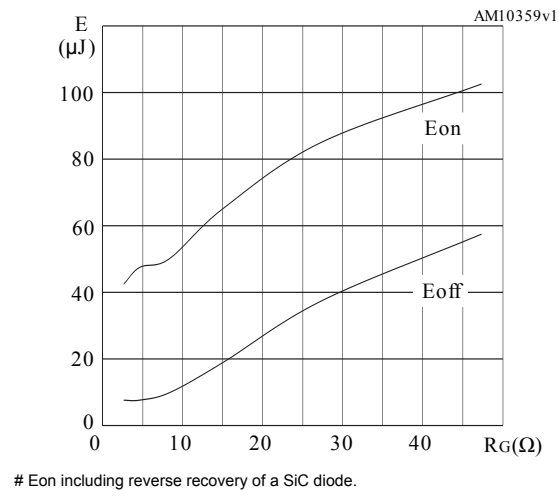
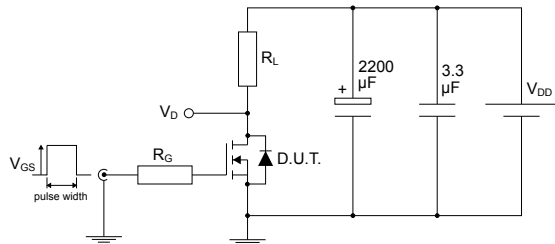


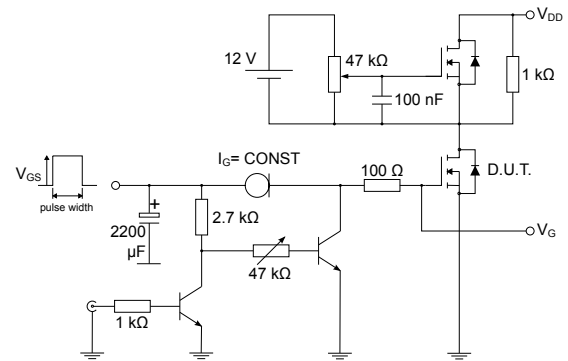
Figure 13. Switching energy vs gate resistance



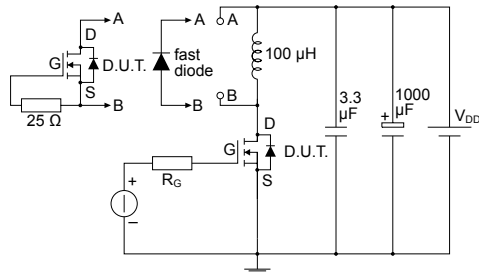
3 Test circuits

Figure 14. Test circuit for resistive load switching times


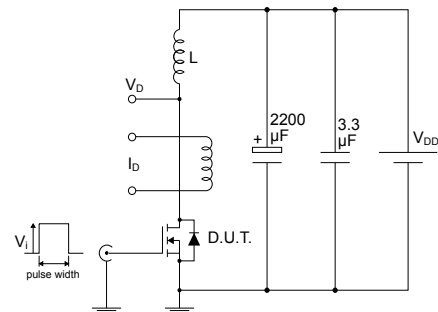
AM01468v1

Figure 15. Test circuit for gate charge behavior


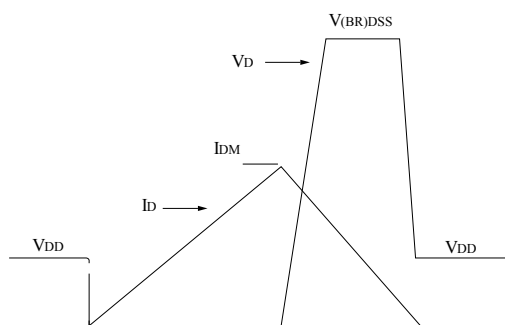
AM01469v1

Figure 16. Test circuit for inductive load switching and diode recovery times


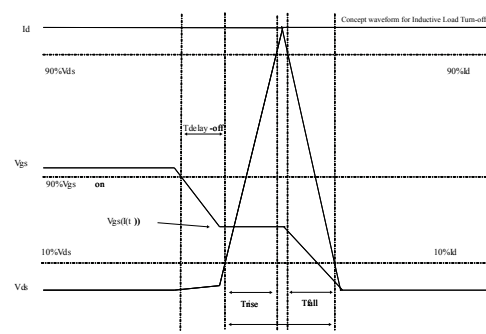
AM01470v1

Figure 17. Unclamped inductive load test circuit


AM01471v1

Figure 18. Unclamped inductive waveform


AM01472v1

Figure 19. Switching time waveform


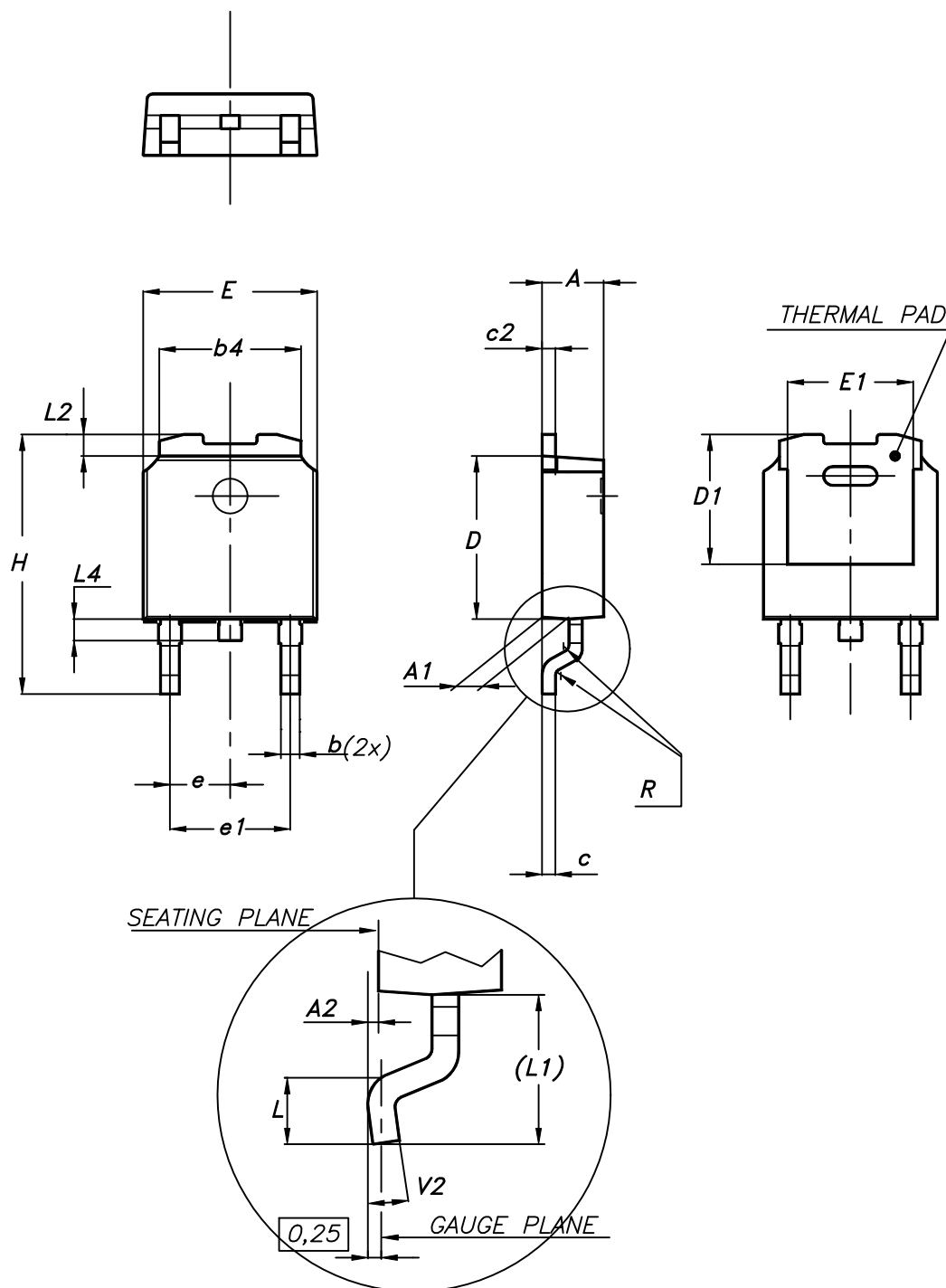
AM05540v2

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK®** packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 DPAK (TO-252) type A2 package information

Figure 20. DPAK (TO-252) type A2 package outline



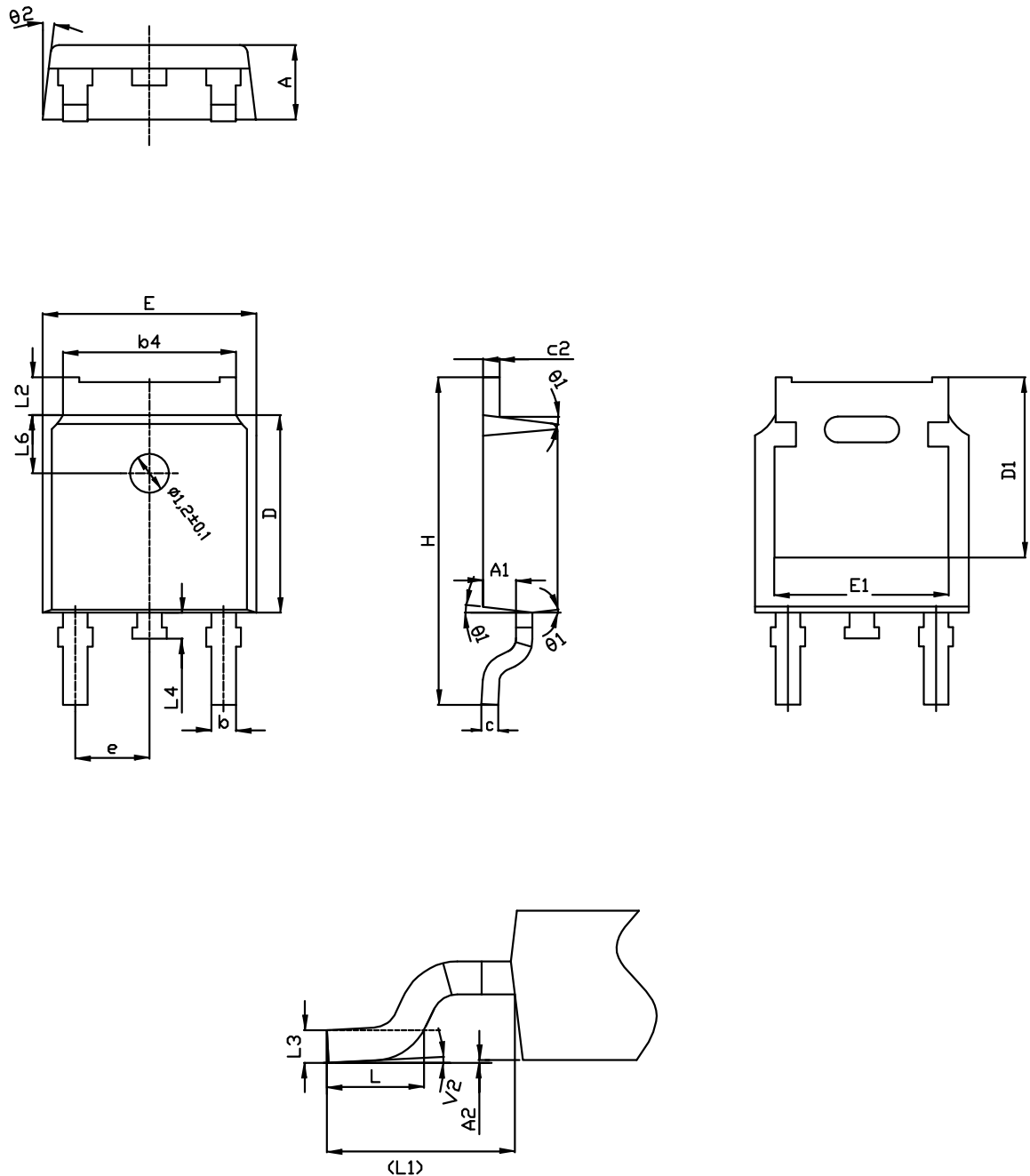
0068772_type-A2_rev25

Table 8. DPAK (TO-252) type A2 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	5.10	5.20	5.30
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
L1	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

4.2 DPAK (TO-252) type C2 package information

Figure 21. DPAK (TO-252) type C2 package outline

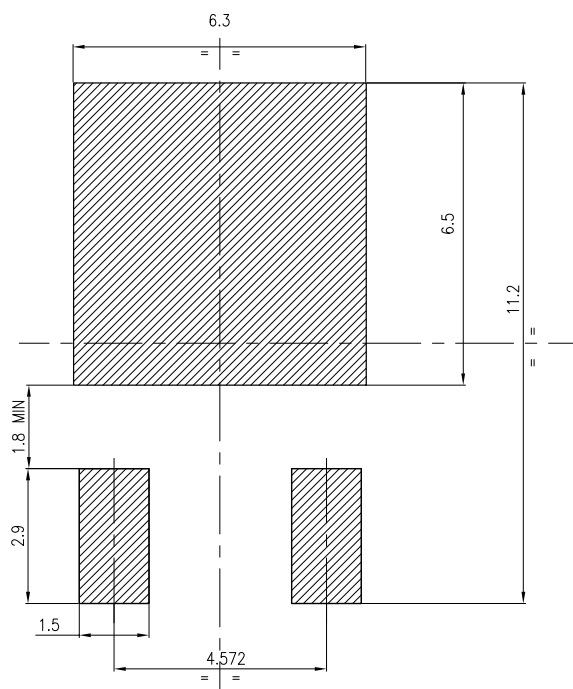


0068772_C2_25

Table 9. DPAK (TO-252) type C2 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0.90	1.01	1.10
A2	0.00		0.10
b	0.72		0.85
b4	5.13	5.33	5.46
c	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.10		5.60
E	6.50	6.60	6.70
E1	5.20		5.50
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.90		1.25
L3	0.51 BSC		
L4	0.60	0.80	1.00
L6	1.80 BSC		
θ1	5°	7°	9°
θ2	5°	7°	9°
V2	0°		8°

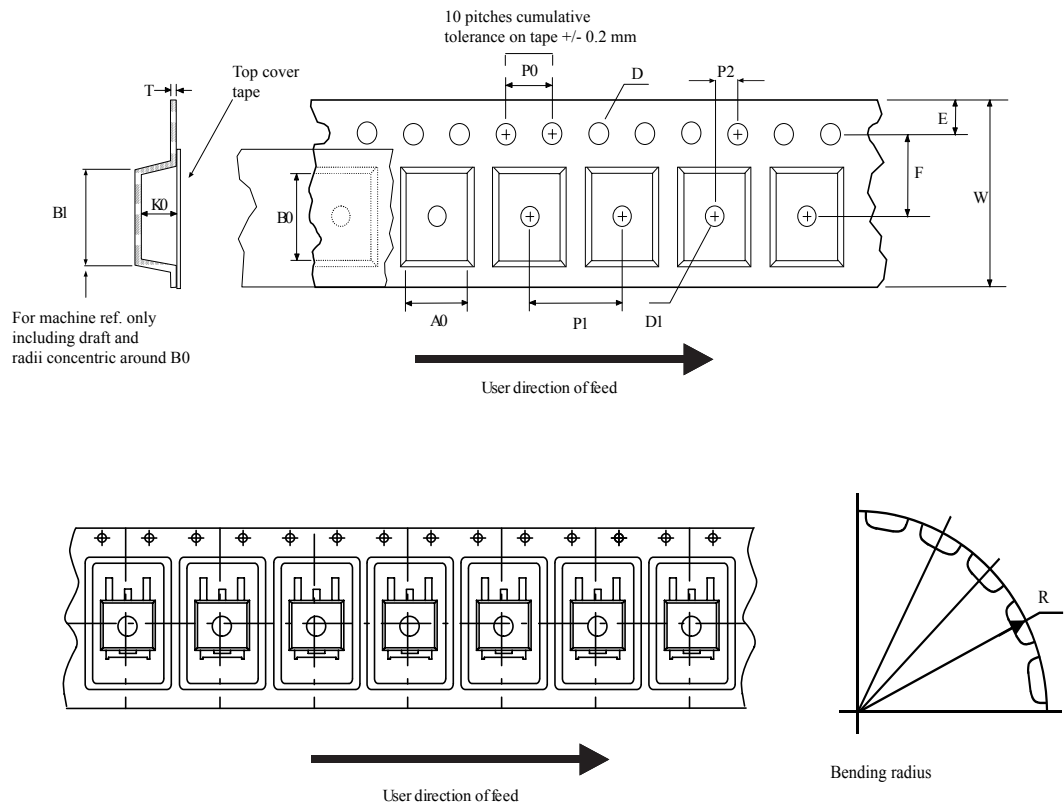
Figure 22. DPAK (TO-252) recommended footprint (dimensions are in mm)



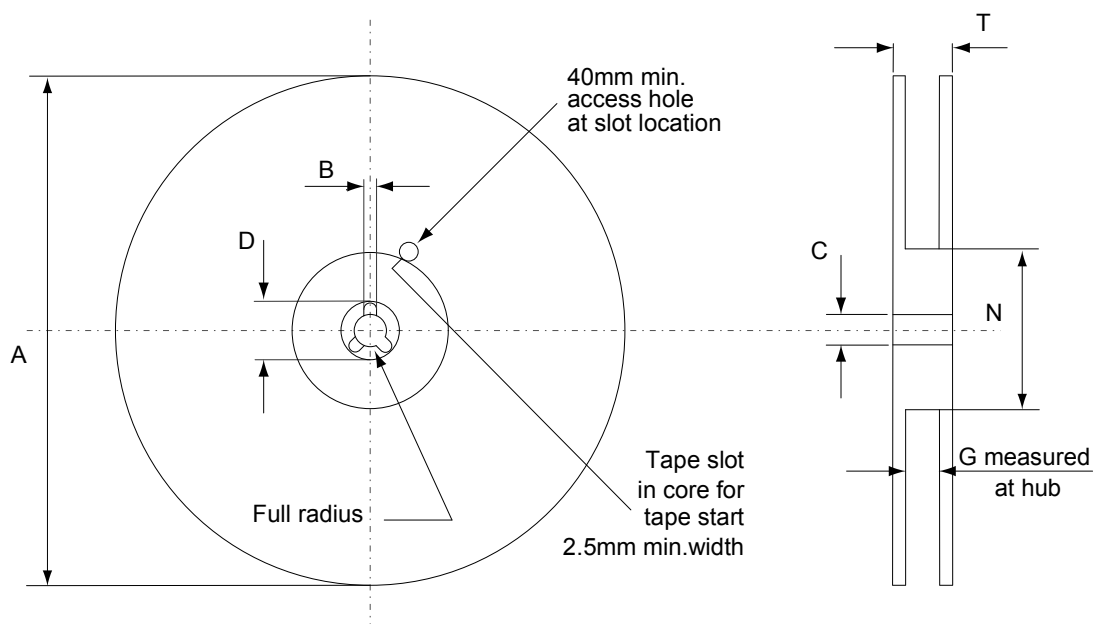
FP_0068772_25

4.3 DPAK (TO-252) packing information

Figure 23. DPAK (TO-252) tape outline



AM08852v1

Figure 24. DPAK (TO-252) reel outline


AM06038v1

Table 10. DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

Revision history

Table 11. Document revision history

Date	Version	Changes
09-Nov-2010	1	First release.
14-Oct-2011	2	Modified <i>Section 2.1: Electrical characteristics (curves)</i>: – <i>Figure 6, Figure 7, Figure 8, Figure 9, Figure 13 and Figure 14</i> – Added <i>Figure 15</i> Updated $R_{DS(on)}$ value in coverpage and in <i>Table 4</i> Updated values in <i>Table 6</i> Updated <i>Section 4: Package mechanical data</i> and <i>Section 5: Packaging mechanical data</i>. Minor text changes.
20-Nov-2018	3	Removed maturity status indication from cover page. The document status is production data. The part number STB16N65M5 has been moved to a separate datasheet. Updated Section 4 Package information. Minor text changes.

Contents

1	Electrical ratings	2
2	Electrical characteristics.....	3
2.1	Electrical characteristics curves	5
3	Test circuits	8
4	Package information.....	9
4.1	DPAK (TO-252) type A2 package information	9
4.2	DPAK (TO-252) type C2 package information	11
4.3	DPAK (TO-252) packing information.....	14
	Revision history	17

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved